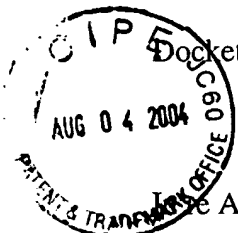


3723



Docket No.: 005917 USA/FET/FET

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor Application of

Young Joseph PAIK

Serial No. 09/998,372

Filed: November 30, 2001

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Group Art Unit: 3723

Examiner: Robert A. Rose

For: CONTROL OF CHEMICAL MECHANICAL POLISHING PAD CONDITIONER
DIRECTIONAL VELOCITY TO IMPROVE PAD LIFE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

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Serial No. 09/998,372

to present to the Office the relevant facts and law regarding the appropriate status of such document.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

Please charge the fee of \$180.00 under 37 CFR 1.17(p) to Deposit Account No. 08-0219. The Commissioner is hereby authorized to charge any additional fees that may be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

Wilmer Cutler Pickering Hale and Dorr LLP



Scott M. Alter

Registration No. 32,879

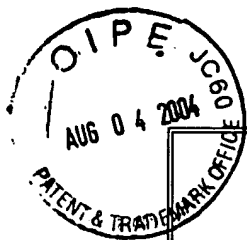
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Washington, DC 20004
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FAX (202) 942-8484
Date: 8/4/04

INFORMATION DISCLOSURE
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APPLICATION
(PTO-1449)ATTY. DOCKET NO.
005917 USA/FET/FETSERIAL NO.
09/998,372APPLICANT
Young Joseph PAIKFILING DATE
November 30, 2001GROUP
3723

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	4,957,605	09/18/90	Hurwitt et al.			04/17/89
	5,240,552	08/31/93	Yu et al.			12/11/91
	5,369,544	11/29/94	Mastrangelo			04/05/93
	5,444,837	08/22/95	Bomans et al.			12/29/93
	5,665,214	09/09/97	Iturralde			05/03/95
	5,695,810	12/09/97	Dubin et al.			11/20/96
	5,824,599	10/20/98	Schacham-Diamand et al.			01/16/96
	5,825,356	10/20/98	Habib et al.			03/18/96
	5,831,851	11/03/98	Eastburn et al.			03/21/95
	5,838,951	11/17/98	Song			08/28/96
	5,859,777	01/12/99	Yokoyama et al.			05/13/97
	5,871,805	02/16/99	Lemelson			04/08/96
	5,943,550	08/24/99	Fulford, Jr. et al.			03/29/96
	6,012,048	01/04/00	Gustin et al.			05/30/97
	6,037,664	03/14/00	Zhao et al.			03/31/98
	6,096,649	08/01/00	Jang			10/25/99
	6,100,195	08/08/00	Chan et al.			12/28/98
	6,114,238	09/05/00	Liao			05/20/98
	6,150,270	11/21/00	Matsuda et al.			01/07/99
	6,157,864	12/05/00	Schwenke et al.			05/08/98
	6,181,013 B1	01/30/01	Liu et al.			03/13/00
	6,212,961 B1	04/10/01	Dvir			02/11/99
	6,226,563 B1	05/01/01	Lim			09/04/98
	6,228,280 B1	05/08/01	Li et al.			05/06/98
	6,237,050 B1	05/22/01	Kim et al.			09/04/98
	6,259,160 B1	07/10/01	Lopatin et al.			04/21/99
	6,281,127 B1	08/28/01	Shue			04/15/99
EXAMINER				DATE CONSIDERED		

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APPLICANT
Young Joseph PAIK

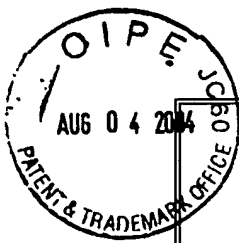
FILING DATE
November 30, 2001

GROUP
3723

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,317,643 B1	11/13/01	Dmochowski			03/31/99
	6,339,727 B1	01/15/02	Ladd			12/21/98
	6,355,559 B1	03/12/02	Havemann et al.			11/03/00
	6,391,780 B1	05/21/02	Shih et al.			08/23/99
	6,417,014 B1	07/09/02	Lam et al.			10/19/99
	6,427,093 B1	07/30/02	Toprac			10/07/99
	6,432,728 B1	08/13/02	Tai et al.			10/16/00
	6,449,524 B1	09/10/02	Miller et al.			01/04/00
	6,455,415 B1	09/24/02	Lopatin et al.			04/16/01
	2002/0165636 A1	11/07/02	Hasan			04/24/02
	6,484,064 B1	11/19/02	Campbell			10/05/99
	6,495,452 B1	12/17/02	Shih			08/18/99
	2002/0193899 A1	12/19/02	Shanmugasundram et al.			05/01/02
	2003/0017256 A1	01/23/03	Shimane			06/12/02
	6,515,368 B1	02/04/03	Lopatin et al.			12/07/01
	6,528,409 B1	03/04/03	Lopatin et al.			04/29/02
	6,537,912 B1	03/25/03	Agarwal			08/25/00
	6,580,958 B1	06/17/03	Takano			11/22/99
	6,605,549 B2	08/12/03	Leu et al.			09/29/01
	6,607,976 B2	08/19/03	Chen et al.			09/25/01
	6,609,946 B1	08/26/03	Tran			07/14/00
	6,624,075 B1	09/23/03	Lopatin et al.			11/05/02
	6,630,741 B1	10/07/03	Lopatin et al.			12/07/01
	6,660,633 B1	12/09/03	Lopatin et al.			02/26/02
	6,708,074 B1	03/16/04	Chi et al.			08/11/00
	6,708,075 B2	03/16/04	Sonderman et al.			11/16/01
	6,728,587 B2	04/27/04	Goldman et al.			12/27/00
EXAMINER				DATE CONSIDERED		

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.



INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 005917 USA/FET/FET		SERIAL NO. 09/998,372	
				APPLICANT Young Joseph PAIK			
				FILING DATE November 30, 2001		GROUP 3723	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	EP 0 932 195 A1	07/28/99	EP			X	
	EP 1 083 470 A2	03/14/01	EP			X	
	GB 2 365 215 A	02/13/02	GB			X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	Sun, S.C. 1998. "CVD and PVD Transition Metal Nitrides as Diffusion Barriers for Cu Metallization." <i>IEEE</i> . pp. 243-246.						
	Tagami, M., A. Furuya, T. Onodera, and Y. Hayashi. 1999. "Layered Ta-nitrides (LTN) Barrier Film by Power Swing Sputtering (PSS) Technique for MOCVD-Cu Damascene Interconnects." <i>IEEE</i> . pp. 635-638.						
	Yamagishi, H., Z. Tokei, G.P. Beyer, R. Donaton, H. Bender, T. Nogami, and K. Maex. 2000. "TEM/SEM Investigation and Electrical Evaluation of a Bottomless I-PVD TA(N) Barrier in Dual Damascene" (Abstract). <i>Advanced Metallization Conference 2000</i> . San Diego, CA.						
	Eisenbraun, Eric, Oscar van der Straten, Yu Zhu, Katharine Dovidenko, and Alain Kaloyeros. 2001. "Atomic Layer Deposition (ALD) of Tantalum-Based Materials for Zero Thickness Copper Barrier Applications" (Abstract). <i>IEEE</i> . pp. 207-209.						
	Smith, S.R., K.E. Elers, T. Jacobs, V. Blaschke, and K. Pfeifer. 2001. "Physical and Electrical Characterization of ALD Tin Used as a Copper Diffusion Barrier in 0.25 μm, Dual Damascene Backend Structures" (Abstract). <i>Advanced Metallization Conference 2001</i> . Montreal, Quebec.						
	Kim, Y.T. and H. Sim. 2002. "Characteristics of Pulse Plasma Enhanced Atomic Layer Deposition of Tungsten Nitride Diffusion Barrier for Copper Interconnect" (Abstract). <i>IEIC Technical Report</i> . Vol. 102, No. 178, pp. 115-118.						
	Elers, Kai-Erik, Ville Saanila, Pekka J. Soininen, Wei-Min Li, Juhana T. Kostamo, Suvi Haukka, Jyrki Juhanoja, and Wim F.A. Besling. 2002. "Diffusion Barrier Deposition on a Copper Surface by Atomic Layer Deposition" (Abstract). <i>Advanced Materials</i> . Vol. 14, No. 13-14, pp. 149-153.						
	Peng, C.H., C.H. Hsieh, C.L. Huang, J.C. Lin, M.H. Tsai, M.W. Lin, C.L. Chang, Winston S. Shue, and M.S. Liang. 2002. "A 90nm Generation Copper Dual Damascene Technology with ALD TaN Barrier." <i>IEEE</i> . pp. 603-606.						
	Van der Straten, O., Y. Zhu, E. Eisenbraun, and A. Kaloyeros. 2002. "Thermal and Electrical Barrier Performance Testing of Ultrathin Atomic Layer Deposition Tantalum-Based Materials for Nanoscale Copper Metallization." <i>IEEE</i> . pp. 188-190.						
	Wu, Z.C., Y.C. Lu, C.C. Chiang, M.C. Chen, B.T. Chen, G.J. Wang, Y.T. Chen, J.L. Huang, S.M. Jang, and M.S. Liang. 2002. "Advanced Metal Barrier Free Cu Damascene Interconnects with PECVD Silicon Carbide Barriers for 90/65-nm BEOL Technology." <i>IEEE</i> . pp. 595-598.						
	July 25, 2003. International Search Report for PCT/US02/24858.						
	March 30, 2004. Written Opinion for PCT/US02/19062.						
	April 9, 2004. Written Opinion for PCT/US02/19116.						
EXAMINER				DATE CONSIDERED			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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GROUP
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OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

April 28, 2004. Written Opinion for PCT/US02/19117.

May 5, 2004. Office Action for U.S. Serial No. 09/943,955, filed August 31, 2001.

May 5, 2004. International Preliminary Examination Report for PCT/US01/27406.

May 28, 2004. Office Action for U.S. Serial No. 09/943,383, filed August 31, 2001.

June 3, 2004. Office Action for U.S. Serial No. 09/928,474, filed August 14, 2001.

June 23, 2004. Office Action for U.S. Serial No. 10/686,589, filed October 17, 2003.

June 30, 2004. Office Action for U.S. Serial No. 09/800,980, filed March 8, 2001.

July 12, 2004. Office Action for U.S. Serial No. 10/173,108, filed June 8, 2002.

EXAMINER

DATE CONSIDERED

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